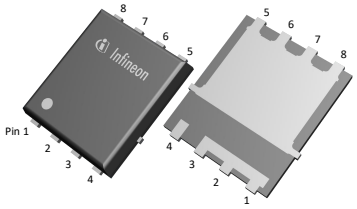
MOSFET

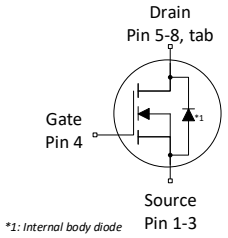
PG-TDSON-8

OptiMOS™ 7 Power-Transistor, 40 V



Features

- N-channel, normal level
- Enhanced SOA
- Drives optimized
- Superior thermal resistance
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



Product validation

Qualified for industrial applications according to the relevant tests of JEDEC JESD47, JESD22 and J-STD-020.

Table 1 Key performance parameters

Parameter	Value	Unit
V_{DS}	40	V
$R_{DS(on),max}$	1.63	mΩ
I_D	174	A
Q_{OSS}	47	nC
$Q_G(0V..10V)$	37	nC
$Q_{rr}(100A/\mu s)$	25	nC

Part number	Package	Marking	Related links
ISC016N04NM7V	PG-TDSON-8	16N04NM7	-

Table of contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Continuous drain current [1]	I_D	-	-	174	A	V_{GS}=10 V, T_C=25 °C
				123		V_{GS}=10 V, T_C=100 °C
				129		V_{GS}=15 V, T_C=100 °C
				31		V_{GS}=10 V, T_A=25 °C, R_{THJA}=50 °C/W [2]
Pulsed drain current [3]	$I_{D,pulse}$	-	-	696	A	T_C=25 °C
Avalanche energy, single pulse [4]	E_{AS}	-	-	68	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	94	W	T_C=25 °C
				3.0		T_A=25 °C, R_{thJA}=50 °C/W [2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

[3] See Diagram 3 for more detailed information

[4] See Diagram 13 for more detailed information

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	-	1.6	°C/W	-
Thermal resistance, junction - case, top	R_{thJC}			20		
Thermal resistance, junction - ambient, 6 cm^2 cooling area [5)]	R_{thJA}			50		

[5)] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	40	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.35	2.75	3.15	V	V_{DS}=V_{GS}, I_D=35 µA
Zero gate voltage drain current	I_{DSS}	-	0.1	1	µA	V_{DS}=40 V, V_{GS}=0 V, T_j=25 °C
			10	100		V_{DS}=40 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	1.31	1.49	mΩ	V_{GS}=15 V, I_D=50 A
			1.47	1.63		V_{GS}=10 V, I_D=50 A
Gate resistance	R_G	-	0.8	-	Ω	-
Transconductance	g_{fs}	-	100	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=50 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance [6]	C_{iss}	-	2400	-	pF	V_{GS}=0 V, V_{DS}=20 V, f=1 MHz
Output capacitance [6]	C_{oss}		1300			
Reverse transfer capacitance [6]	C_{rss}		30			
Turn-on delay time	$t_{d(on)}$	-	8.8	-	ns	V_{DD}=20 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r		3.5			
Turn-off delay time	$t_{d(off)}$		14			
Fall time	t_f		4.9			

[6] Defined by design. Not subject to production test.

Table 6 Gate charge characteristics [7]

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	12	-	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$		6.7	-	nC	
Gate to drain charge	Q_{gd}		8.2	-	nC	
Switching charge	Q_{sw}		14	-	nC	
Gate charge total [8]	Q_g		37	46	nC	
Gate plateau voltage	$V_{plateau}$		5.1	-	V	
Gate charge total, sync. FET	$Q_{g(sync)}$	-	34	-	nC	V_{DS}=0.1 V, V_{GS}=0 to 10 V
Output charge	Q_{oss}	-	47	-	nC	V_{DS}=20 V, V_{GS}=0 V

[7] See "Gate charge waveforms" for parameter definition

[8] Defined by design. Not subject to production test.

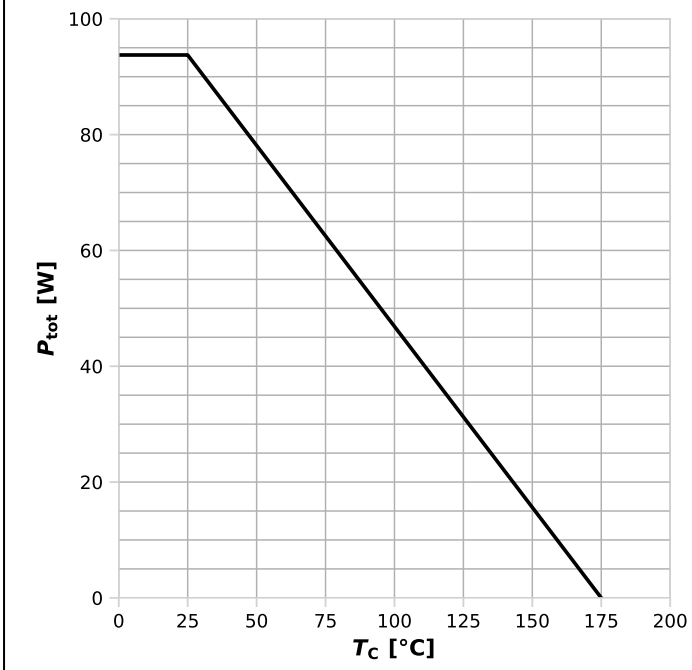
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	92	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$			696		
Diode forward voltage	V_{SD}	-	0.83	1.0	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time [9]	t_{rr}	-	35	-	ns	V_R=20 V, I_F=50 A, di_F/dt=100 A/µs
Reverse recovery charge [9]	Q_{rr}		25		nC	

[9] Defined by design. Not subject to production test.

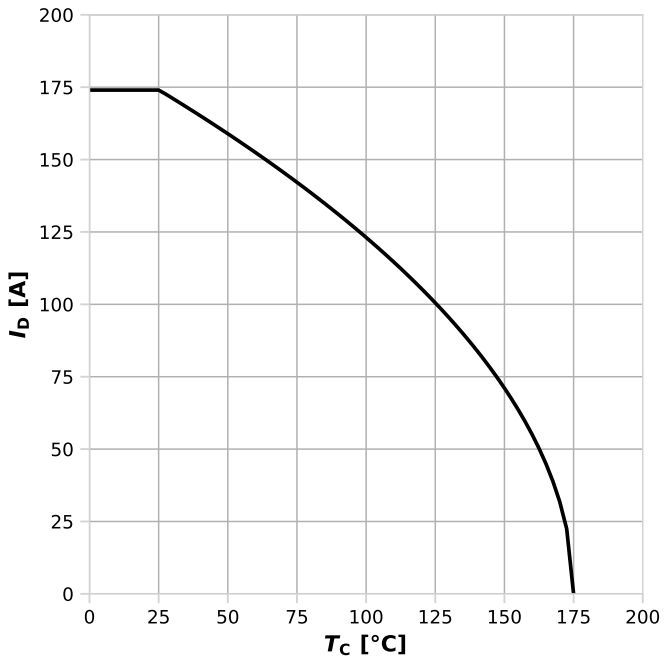
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



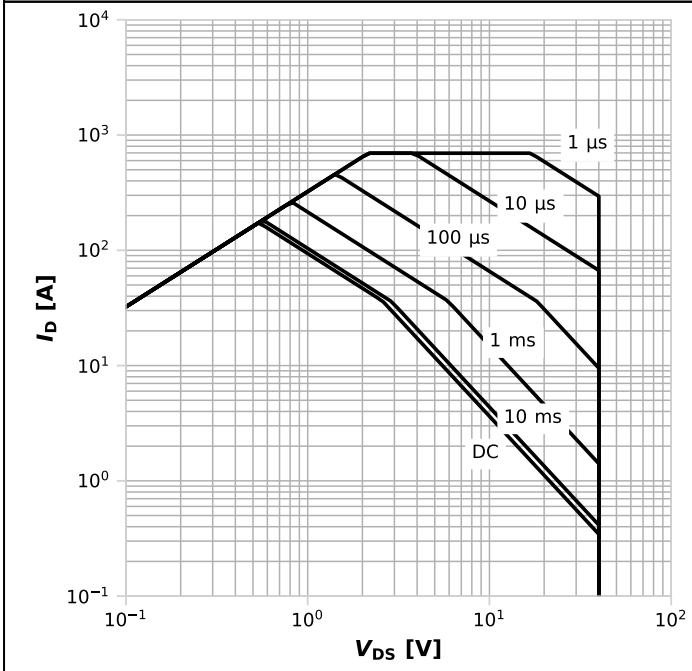
P_{tot}=f(T_C)

Diagram 2: Drain current



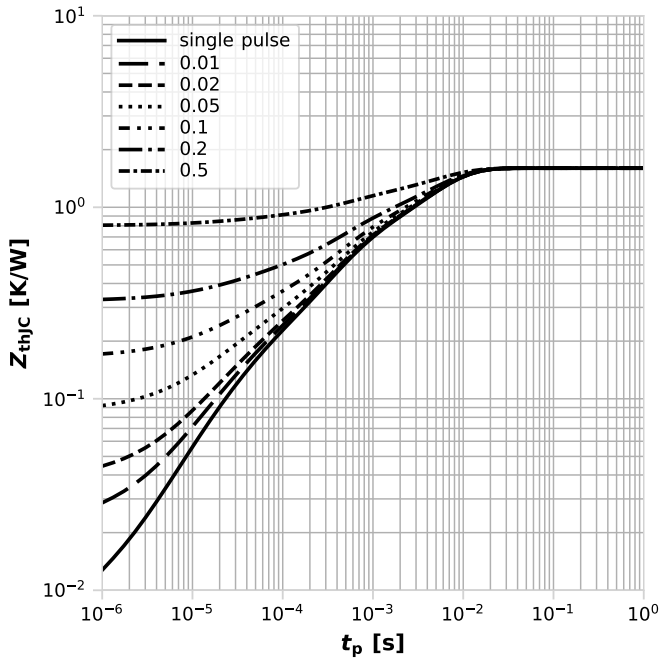
I_D=f(T_C); V_{GS}≥10 V

Diagram 3: Safe operating area



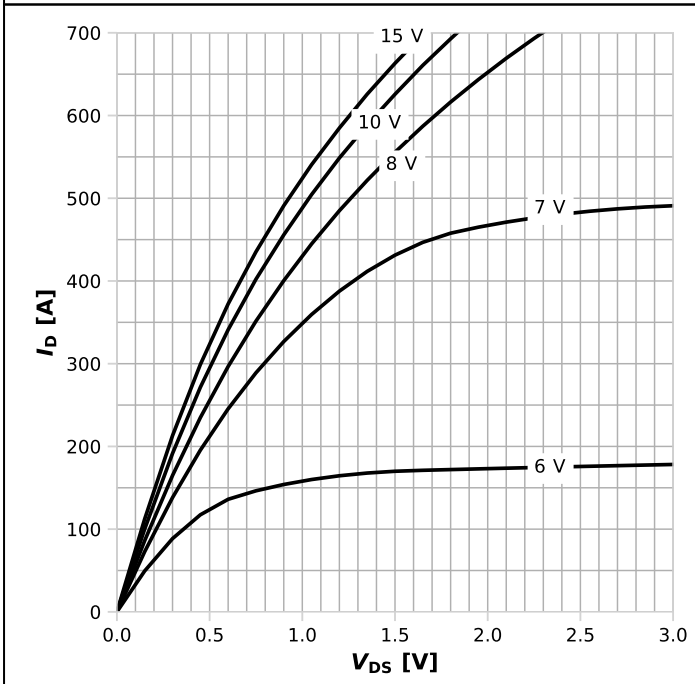
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 4: Max. transient thermal impedance



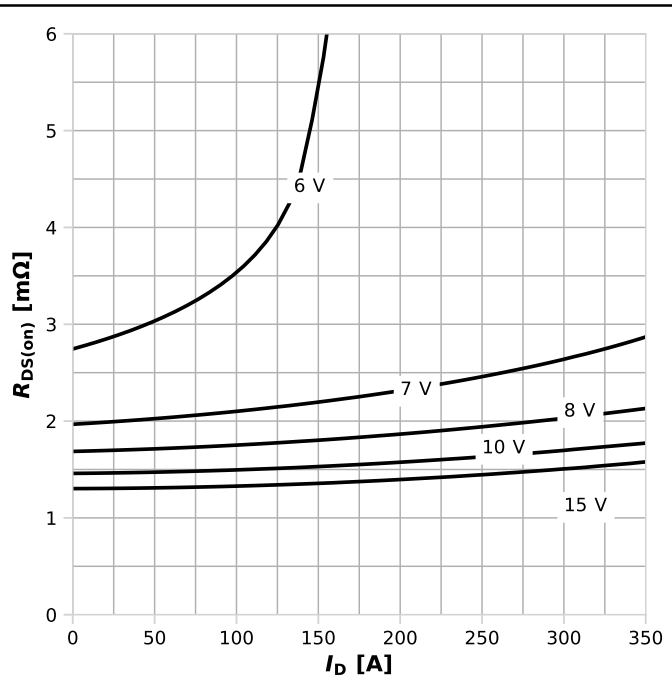
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 5: Typ. output characteristics



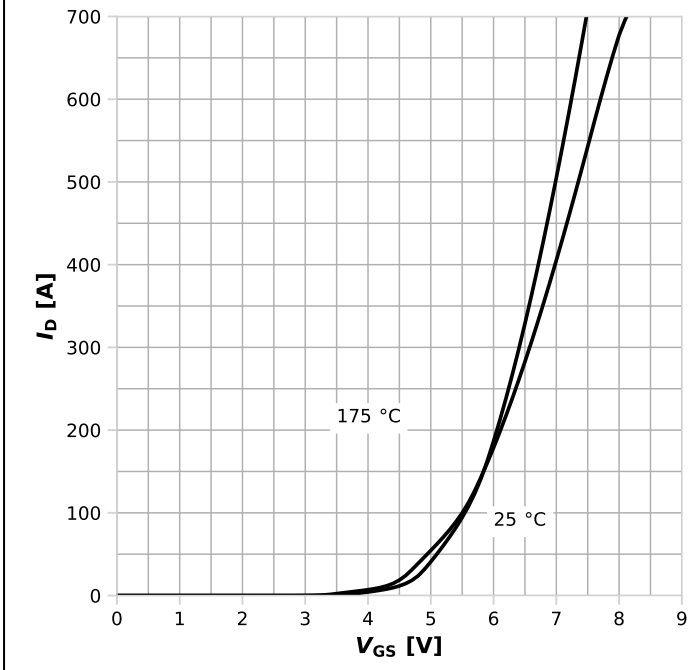
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



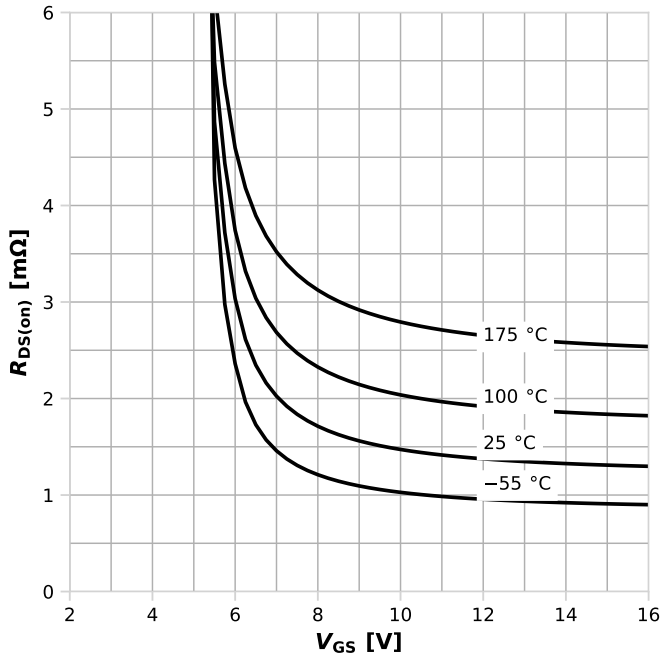
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



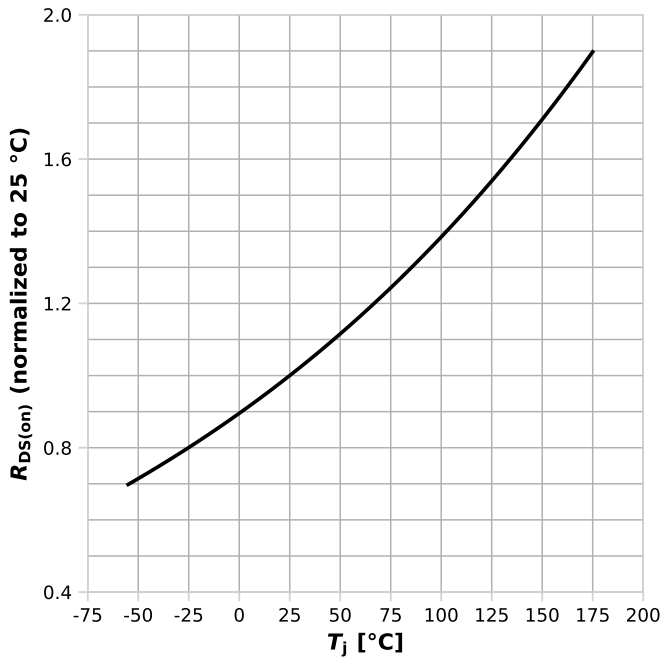
I_D=f(V_{GS}), $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



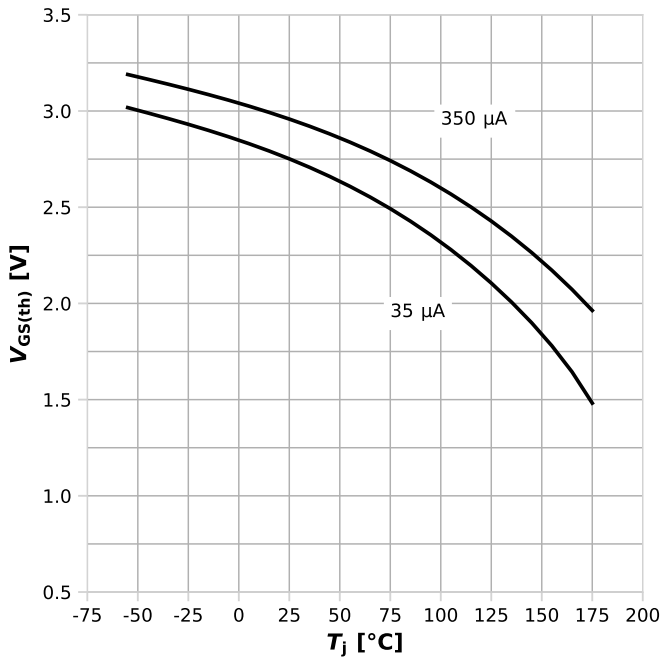
$R_{DS(on)}$=f(V_{GS}), I_D=50 A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



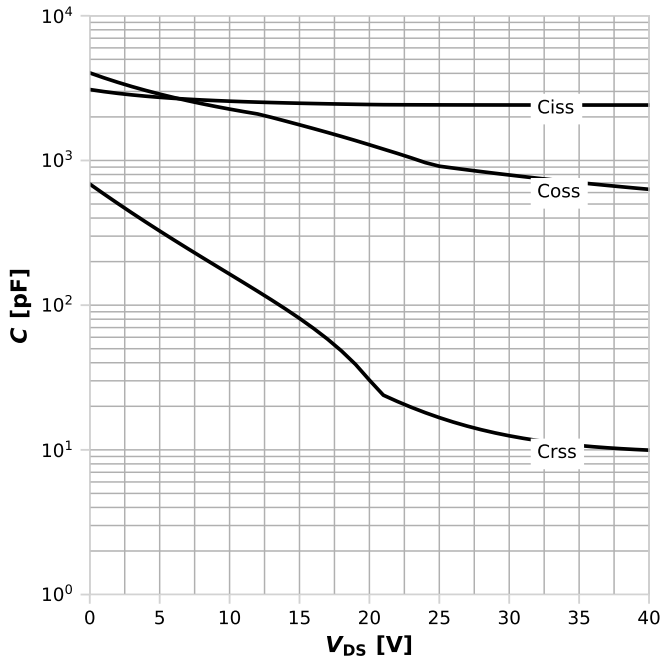
$R_{DS(on)}$=f(T_j), I_D=50 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



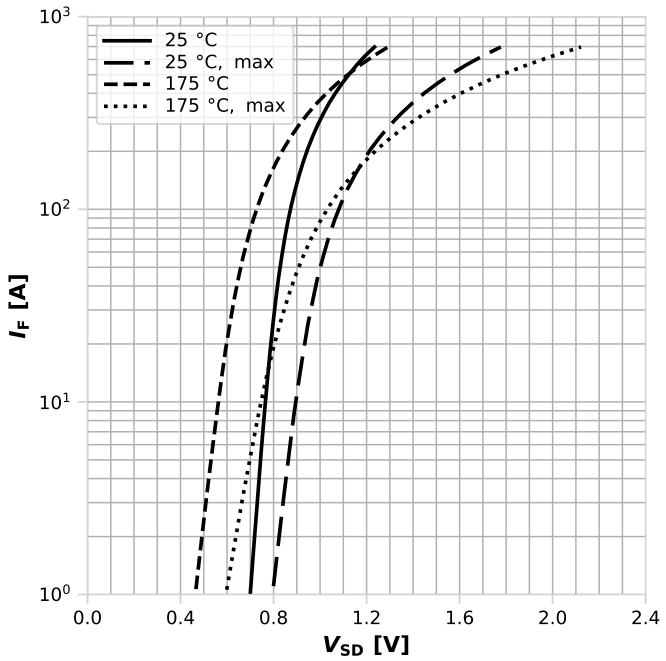
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

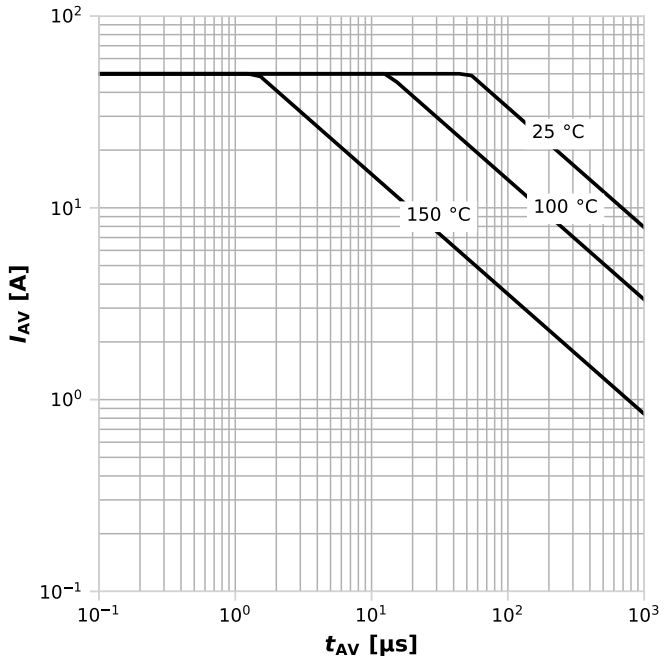
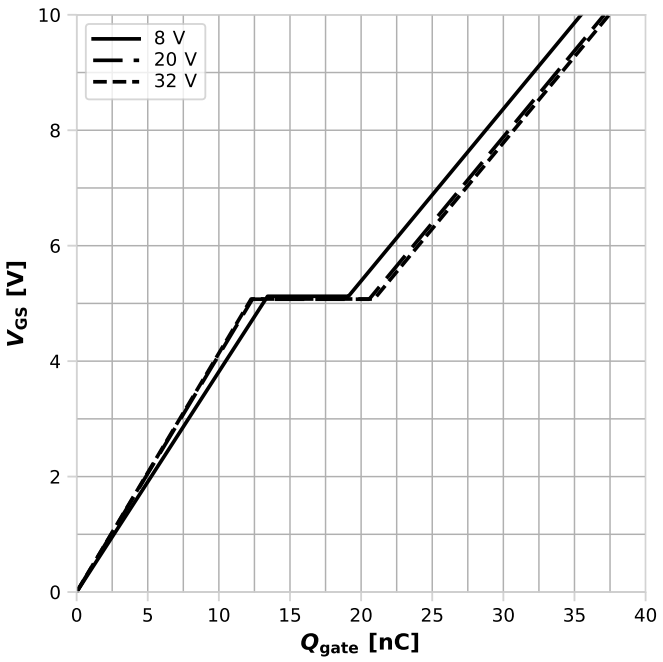
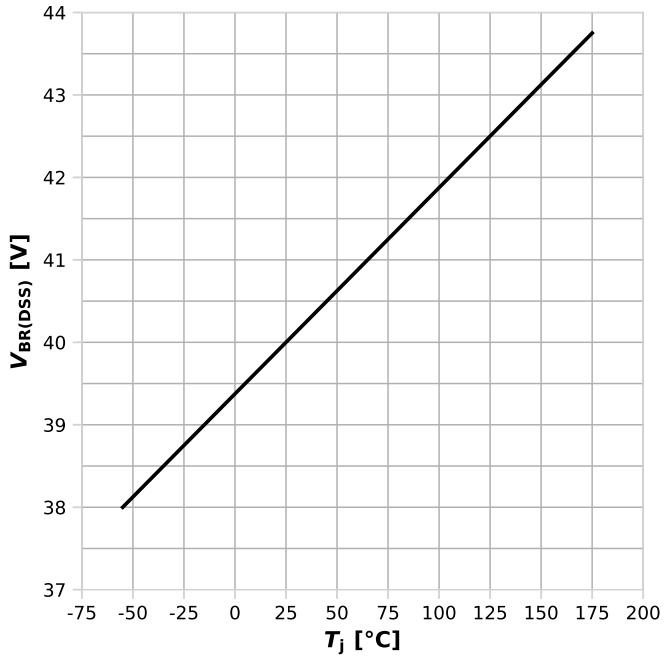
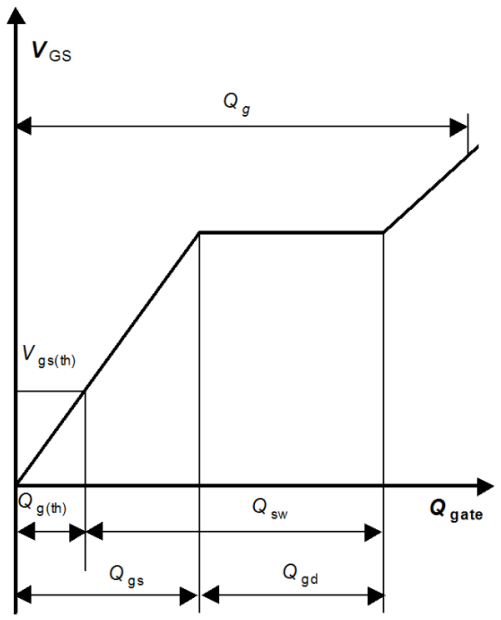
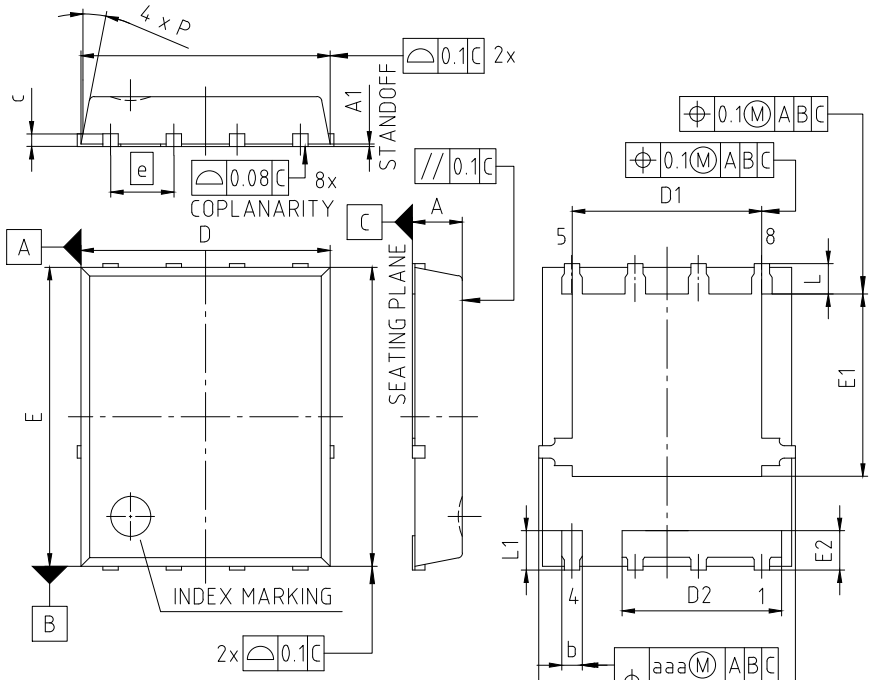
Diagram 13: Avalanche characteristics	Diagram 14: Typ. gate charge
	
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$	V_{GS}=f(Q_{gate}), I_D=50 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Min. drain-source breakdown voltage	Gate charge waveforms
	
$V_{BR(DSS)}$=f(T_j); I_D=1 mA	-

5 Package outlines



PACKAGE - GROUP NUMBER:	PG-TDSON-8-U04	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.20
A1	0	0.05
b	0.26	0.54
c	0.15	0.35
D	4.80	5.35
D1	3.70	4.40
D2	2.94	3.25
D3	4.80	5.15
E	5.70	6.10
E1	3.40	3.76
E2	0.69	0.90
e	1.27	
L	0.45	0.72
L1	0.69	0.90
aaa	0.10	0.25
P	8°	12°

1) EXCLUDING MOLD FLASH
2) REMOVAL ON MOLD GATE
   INTRUSION 0.1 MM
   PROTRUSION 0.1 MM
3) LEAD LENGTH UP TO ANTI FLASH LINE
4) ALL METAL SURFACES ARE PLATED,
   EXCEPT AREA OF CUT

Figure 1 Outline PG-TDSON-8, dimensions in mm

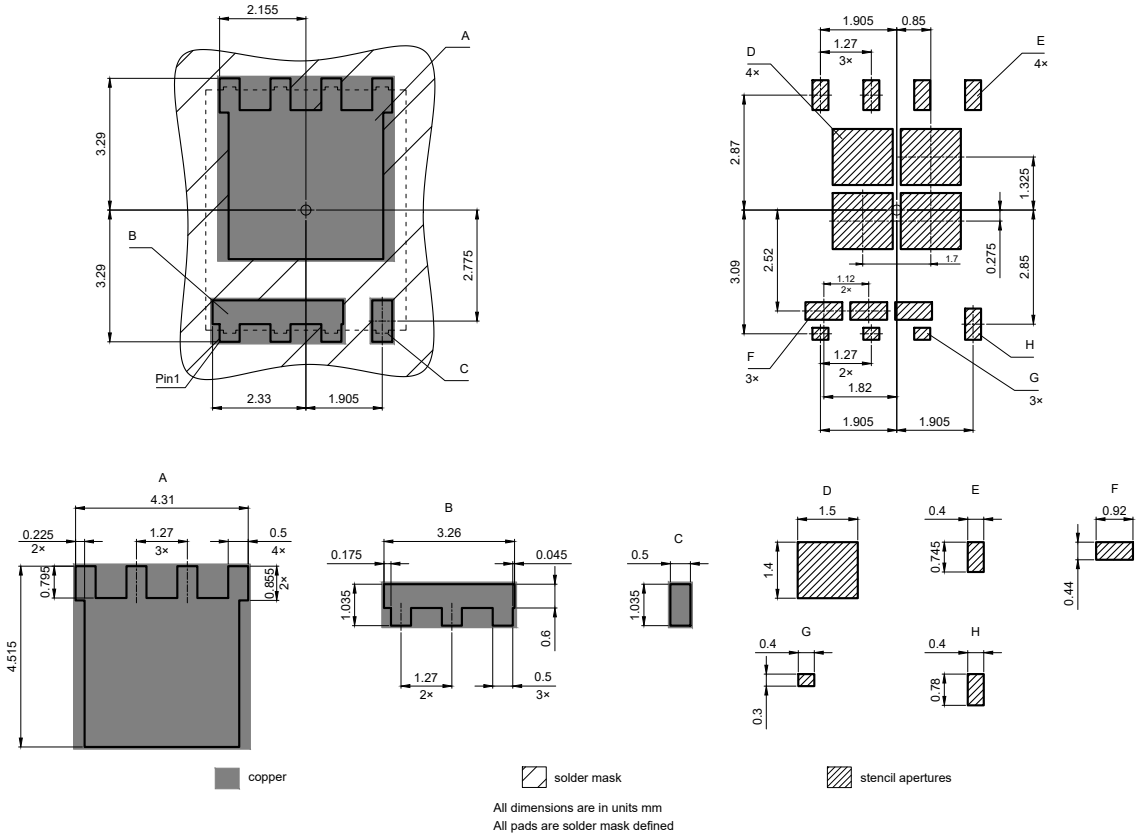


Figure 2 Footprint drawing PG-TDSON-8, dimensions in mm

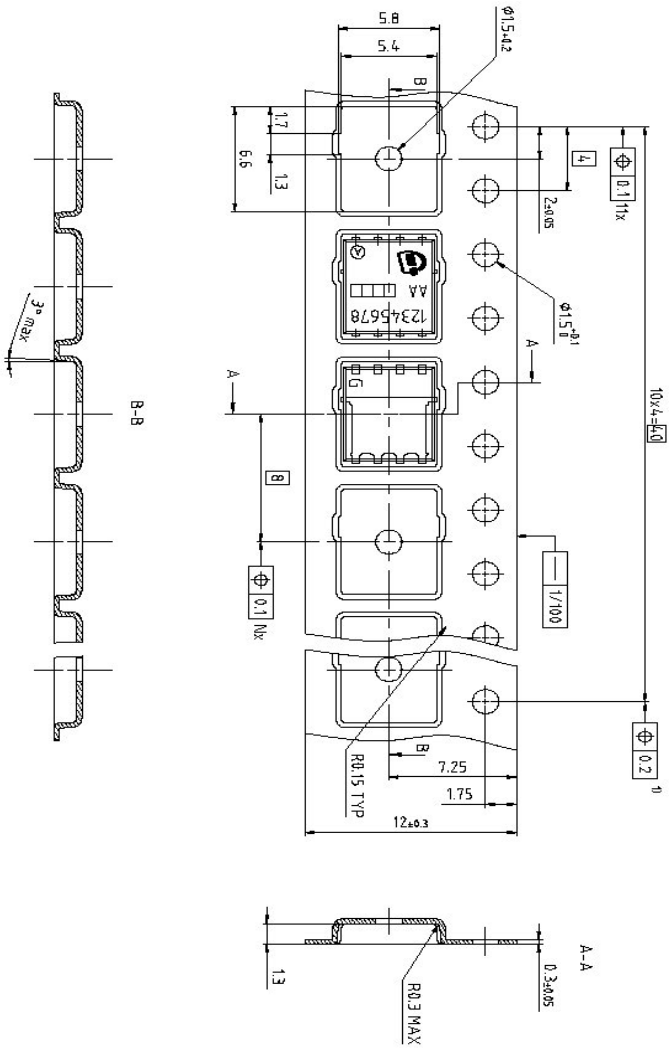


Figure 3 Packaging variant PG-TDSON-8, dimensions in mm

Revision history

ISC016N04NM7V

Revision 2025-04-22, Rev. 1.0

Previous revisions

Revision	Date	Subjects (major changes since last revision)
1.0	2025-04-22	Release of final version

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Published by
Infineon Technologies AG
81726 München, Germany

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